

CLAIM AMENDMENTS

IN THE CLAIMS

This listing of the claims will replace all prior versions, and listing, of claims in the application or previous response to office action:

1-5. (Cancelled)

6. **(Currently Amended)** A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;

wherein the through-bores are approximately 20 μ m in size;

through-connecting, wherein an electrically conductive general layer is built up;

etching a strip conductor image into the electrically conductive general layer;

filling of the bores of the through-connections with a medium;

lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;

applying an insulating lacquer to the surfaces of the circuit board; and

producing strip conductors arranged above the through-connections,

wherein **no layers are applied to the circuit board** between the steps of etching and applying an insulating lacquer ~~no further layers are applied to said circuit boards.~~

7. (Previously Presented) The method as claimed in claim 6, wherein the medium used in filling the bores and insulating lacquer is identical.

8. (Previously Presented) The method as claimed in claim 6, wherein the medium used in filling the bores and the insulating lacquer is non-resistant to etching.

9. (Previously Presented) The method as claimed in claim 6 wherein the strip conductors arranged above the through-connections are carbon.

10. (Previously Presented) The method as claimed in claim 6, further comprising separating individual circuit boards by means of a milling process.

11. **(Cancelled)**

12. (Previously Presented) The method as claimed in claim 6, wherein the insulating lacquer is an International Standard Organization lacquer.

13. **(Currently Amended)** A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;

wherein the through-bores are approximately 20 μ m in size;

through-connecting, wherein an electrically conductive general layer is built up;

etching a strip conductor image into the electrically conductive general layer;

filling of the bores of the through-connections with a medium;

without brushing **the electrically conductive general layer of the** circuit board, lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;

applying an insulating lacquer to the surfaces of the circuit board; and

producing strip conductors arranged above the through-connections.

14. (Previously Presented) The method as claimed in claim 13, wherein the medium used in filling the bores and insulating lacquer is identical.

15. (Previously Presented) The method as claimed in claim 13, wherein the medium used in filling the bores and the insulating lacquer is non-resistant to etching.

16. (Previously Presented) The method as claimed in claim 13, wherein the strip conductors arranged above the through-connections are carbon.

17. (Previously Presented) The method as claimed in claim 13, further comprising separating individual circuit boards by means of a milling process.

18. **(Cancelled)**

19. (Previously Presented) The method as claimed in claim 13, wherein the insulating lacquer is an International Standard Organization lacquer.

20. **(Currently Amended)** A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;

wherein the through-bores are approximately 20 μ m in size;

through-connecting, wherein an electrically conductive general layer is built up;

etching a strip conductor image into the electrically conductive general layer;

filling of the bores of the through-connections with a medium;

without brushing **the electrically conductive general layer of the said** circuit board, lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;

applying an insulating lacquer to the surfaces of the circuit board; and

producing strip conductors arranged above the through-connections,

wherein between the steps of etching and applying an insulating lacquer no further layers are applied to said circuit boards.

21. (Previously Presented) The method as claimed in claim 20, wherein the medium used in filling the bores and insulating lacquer is identical.

22. (Previously Presented) The method as claimed in claim 20, wherein the medium used in filling the bores and the insulating lacquer is non-resistant to etching.

23. (Previously Presented) The method as claimed in claim 20, wherein the strip conductors arranged above the through-connections are carbon.

24. (Previously Presented) The method as claimed in claim 20, further comprising separating individual circuit boards by means of a milling process.

25. **(Cancelled)**

26. **(New)** A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;

through-connecting, wherein an electrically conductive general layer is built up;

etching a strip conductor image into the electrically conductive general layer;

filling of the bores of the through-connections with a medium;

lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;

applying an insulating lacquer to the surfaces of the circuit board; and

producing strip conductors arranged above the through-connections,

wherein no layers are applied to the circuit board between the steps of etching and applying an insulating lacquer; and

wherein the electrically conductive layer is not coarsened between the steps of etching and applying an insulating layer.